

	L #	Hits	EAST Search Text	DBs	Time Stamp	Type
1	L1	718	(356/237.3-237.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
2	L2	1349	(382/144-149).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
3	L3	649	(348/125,126,128).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
4	L4	37988	("700").CLAS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 12:50	IS&R
5	L5	78	(L1 OR L2 OR L3) AND L4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:41	BRS
6	L6	14	("4541115"   "4817175"   "5384463"   "5430292"   "5557105"   "5699447"   "5799111" "5825482"   "5892224"   "6031607"   "6252412"   "6465783"   "6538248"	USPAT	2004/08/06 13:06	BRS
7	L7	19	(L1 OR L2 OR L3) AND wafer WITH fragment\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58	BRS
8	L8	11740 6	(camera OR image OR video OR picture OR photo OR photograph) WITH (merg\$3 OR combin\$3 OR join\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 14:58	BRS
9	L9	381	(L1 OR L2 OR L3) AND L8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:04	BRS
10	L1 0	0	(L1 OR L2 OR L3) AND (L8 SAME (cyclical OR recycl\$3 OR recirculat\$3) WITH (memory OR storage OR log OR buffer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:00	BRS
11	L1 1	1	(L1 OR L2 OR L3) AND L8 AND ((cyclical OR recycl\$3 OR recirculat\$3) WITH (memory OR storage OR log OR buffer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:00	BRS
12	L1 2	125	(L1 OR L2 OR L3) AND L8 SAME (memory OR stor\$3 OR log\$4 OR buffer\$4 OR register\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/06 15:05	BRS
13	L1 3	0	6124926.URPN.	USPAT	2004/08/06 15:18	BRS

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	1	Document ID	Source	Issue Date	Title	Current OR	Inventor	2	3	4 [1]	5
1	<input checked="" type="checkbox"/>	US 6535628 B2	USPAT	20030318	Detection of wafer fragments in a wafer processing apparatus	382/149	Smargiassi, Eugene et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
2	<input checked="" type="checkbox"/>	US 20010043735 A1	US-PG PUB	20011122	DETECTION OF WAFER FRAGMENTS IN A WAFER PROCESSING	382/149	SMARGIASSI, EUGENE et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	US 5659630 A	USPAT	19970819	Advanced manufacturing inspection system	382/149	Forslund, Donald Charles	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	US 5644140 A	USPAT	19970701	Apparatus for checking semiconductor wafers with complementary light sources and two cameras	250/559.08	Biedermann, Ernst et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
5	<input checked="" type="checkbox"/>	US 6738506 B2	USPAT	20040518	Image processing system for multi-beam inspection	382/151	Miller, S. Daniel et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	US 6701002 B1	USPAT	20040302	Test method for image pickup devices	382/145	Karube, Koji	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	US 6546308 B2	USPAT	20030408	Method and system for manufacturing semiconductor devices, and method and system for inspecting semiconductor devices	700/121	Takagi, Yuji et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	US 6535776 B1	USPAT	20030318	Method for localizing and isolating an errant process step	700/110	Tobin, Jr., Kenneth W. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	US 6438438 B1	USPAT	20020820	Method and system for manufacturing semiconductor devices, and method and system for inspecting semiconductor devices	700/121	Takagi, Yuji et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	US 6198982 B1	USPAT	20010306	Method and apparatus for detecting the presence of particles on a wafer holder of semiconductor exposure equipment	700/121	Park, Soon-jong et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
11	<input type="checkbox"/>	US 5878151 A	USPAT	19990302	Moving object tracking	382/103	Tang, Qing et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
12	<input type="checkbox"/>	US 6721045 B1	USPAT	20040413	Method and apparatus to provide embedded substrate process monitoring through consolidation of multiple process inspection techniques	356/237.5	Hunter, Reginald	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
13	<input type="checkbox"/>	US 6707545 B1	USPAT	20040316	Optical signal routing method and apparatus providing multiple inspection collection points on semiconductor	356/237.5	Hunter, Reginald	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
14	<input type="checkbox"/>	US 6707544 B1	USPAT	20040316	Particle detection and embedded vision system to enhance substrate yield and throughput	356/237.5	Hunter, Reginald et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
15	<input type="checkbox"/>	US 6697517 B1	USPAT	20040224	Particle detection and embedded vision system to enhance substrate yield and throughput	382/149	Hunter, Reginald	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>

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	1	Document ID	Source	Issue Date	Title	Current OR	Inventor	2	3	4 [1]	5
16	<input type="checkbox"/>	US 6693708 B1	USPAT	20040217	Method and apparatus for substrate surface inspection using spectral profiling techniques	356/237.5	Hunter, Reginald	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
17	<input type="checkbox"/>	US 6630995 B1	USPAT	20031007	Method and apparatus for embedded substrate and system status monitoring	356/237.5	Hunter, Reginald	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
18	<input type="checkbox"/>	US 6760471 B1	USPAT	20040706	Compensation system and related techniques for use in a printed circuit board inspection system	382/147	Raymond, Douglas W.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>
19	<input checked="" type="checkbox"/>	US 6124926 A	USPAT	20000926	Defect detecting method and device	356/237.4	Ogawa, Tomoya et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>

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